

-10-

ELECTRONIC PACKAGE ASSEMBLYAbstract of the Disclosure

An electronic package assembly includes a number of semiconductor devices with first and second sides. A printed circuit substrate has a number of printed circuit patterns bonded to conductive pads of the first sides of the devices. A metal leadframe includes leads which provide external connections for the package assembly, and also includes a non-lead island portion bonded to conductive pads of the second sides of the devices. In this way the island portion of the leadframe forms an interconnection between the second sides of the devices.